

ABSTRACT

To provide a metal base circuit board excellent in heat dissipation properties, which remarkably reduces malfunction time of a semiconductor which occurs when a hybrid integrated circuit is operated at a high frequency.

A metal base circuit board to be use for a hybrid integrated circuit, comprising circuits provided on a metal plate via an insulating layer (A, B), a power semiconductor mounted on the circuit and a control semiconductor to control the power semiconductor, provided on the circuit, wherein a low capacitance portion is embedded under a circuit portion (pad portion) on which the control semiconductor is mounted, preferably, the low capacitance portion is made of a resin containing an inorganic filler and has a dielectric constant of from 2 to 9.